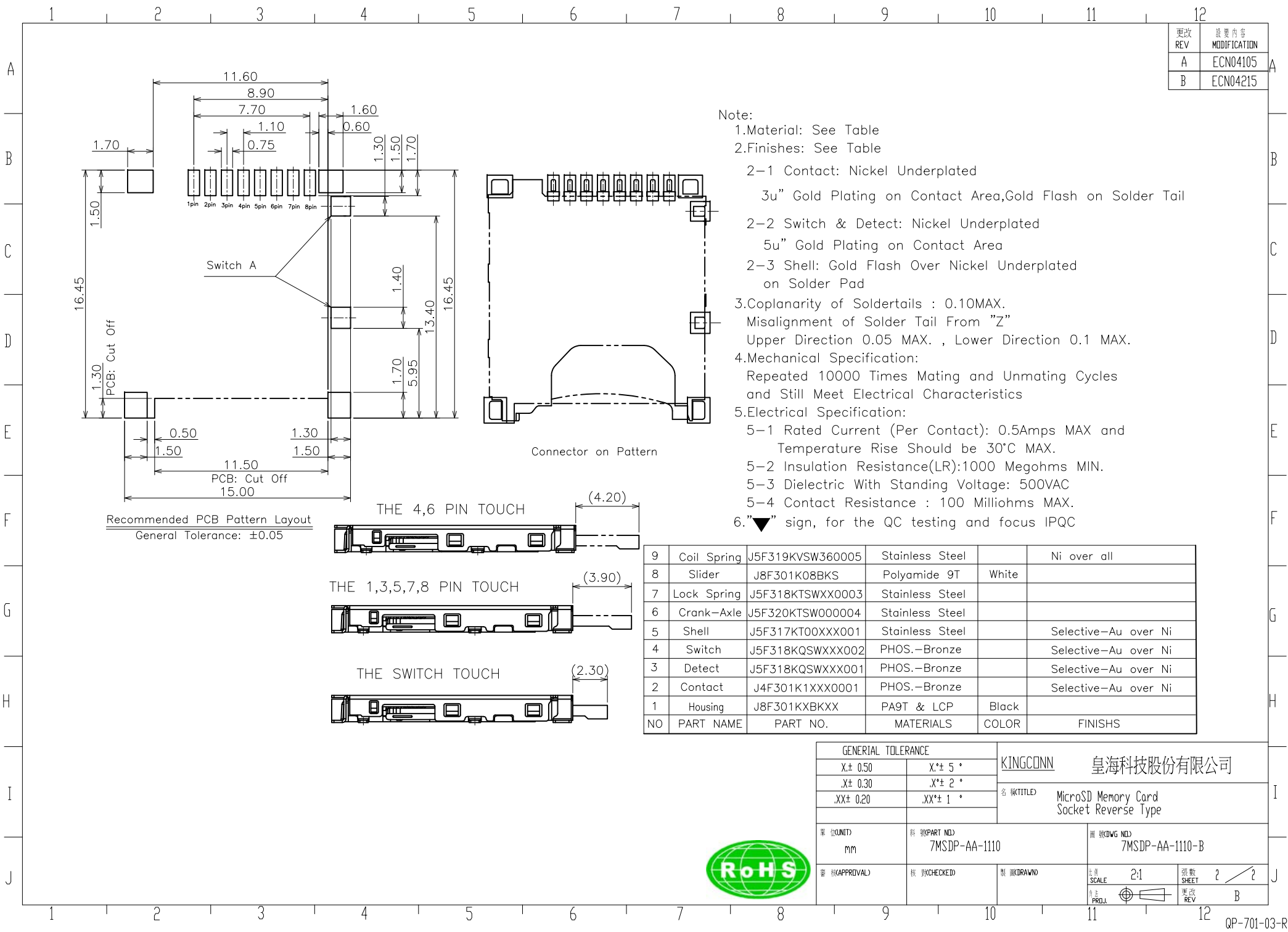




更改 REV	最要内容 MODIFICATION
A	ECN04105
B	ECN04215

- Note:
- 1.Material: See Table
 - 2.Finishes: See Table
 - 2-1 Contact: Nickel Underplated
3u" Gold Plating on Contact Area,Gold Flash on Solder Tail
 - 2-2 Switch & Detect: Nickel Underplated
5u" Gold Plating on Contact Area
 - 2-3 Shell: Gold Flash Over Nickel Underplated
on Solder Pad
 - 3.Coplanarity of Solderails : 0.10MAX.
Misalignment of Solder Tail From "Z"
Upper Direction 0.05 MAX. , Lower Direction 0.1 MAX.
 - 4.Mechanical Specification:
Repeated 10000 Times Mating and Unmating Cycles
and Still Meet Electrical Characteristics
 - 5.Electrical Specification:
5-1 Rated Current (Per Contact): 0.5Amps MAX and
Temperature Rise Should be 30°C MAX.
5-2 Insulation Resistance(LR):1000 Megohms MIN.
5-3 Dielectric With Standing Voltage: 500VAC
5-4 Contact Resistance : 100 Milliohms MAX.
 - 6."▼" sign, for the QC testing and focus IPQC

9	Coil Spring	J5F319KVS360005	Stainless Steel		Ni over all
8	Slider	J8F301K08BKS	Polyamide 9T	White	
7	Lock Spring	J5F318KTSWXX0003	Stainless Steel		
6	Crank-Axle	J5F320KTSW000004	Stainless Steel		
5	Shell	J5F317KT00XXX001	Stainless Steel		Selective-Au over Ni
4	Switch	J5F318KQSWXXX002	PHOS.-Bronze		Selective-Au over Ni
3	Detect	J5F318KQSWXXX001	PHOS.-Bronze		Selective-Au over Ni
2	Contact	J4F301K1XXX0001	PHOS.-Bronze		Selective-Au over Ni
1	Housing	J8F301KXBKXX	PA9T & LCP	Black	
NO	PART NAME	PART NO.	MATERIALS	COLOR	FINISHS

GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5 °	名 (TITLE) MicroSD Memory Card Socket Reverse Type	
X± 0.30	X*± 2 °		
.XX± 0.20	.XX*± 1 °		
单 (UNIT) mm	料 (PART NO) 7MSDP-AA-1110	图 (DWG NO) 7MSDP-AA-1110-B	
审 (APPROVAL)	核 (CHECKED)	制 (DRAWN)	比例 SCALE 2:1
			张数 SHEET 2 / 2
			更改 REV B

